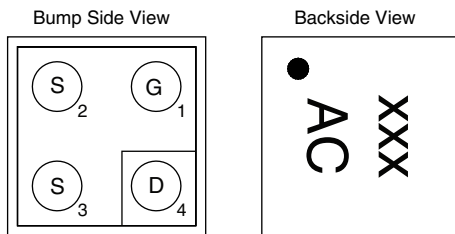




## P-Channel 8 V (D-S) MOSFET

PRODUCT SUMMARY			
$V_{DS}$ (V)	$R_{DS(on)}$ ( $\Omega$ )	$I_D$ (A) <sup>a</sup>	$Q_g$ (Typ.)
- 8	0.068 at $V_{GS} = - 4.5$ V	- 3.1	6.7 nC
	0.088 at $V_{GS} = - 2.5$ V	- 2.7	
	0.155 at $V_{GS} = - 1.5$ V	- 2.1	
	0.290 at $V_{GS} = - 1.2$ V	- 0.5	

### MICRO FOOT



Device Marking: xxx = Date/Lot Traceability Code  
AC

Ordering Information: Si8805EDB-T2-E1 (Lead (Pb)-free and Halogen-free)

### FEATURES

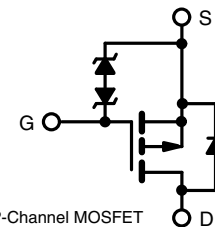
- TrenchFET<sup>®</sup> Power MOSFET
- Ultra Small 0.8 mm x 0.8 mm Outline
- Ultra Thin 0.357 mm Height
- Typical ESD Protection 1500 V HBM
- Material categorization:  
For definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### APPLICATIONS

- Portable Devices such as Cell Phones, Smart Phones, Tablet PCs and Media Players
  - Load Switch for Low Voltage Gate Drive
  - Load Switch for 1.2 V Power Line



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ( $T_A = 25$ °C, unless otherwise noted)				
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	$V_{DS}$	- 8	V	
Gate-Source Voltage	$V_{GS}$	$\pm 5$		
Continuous Drain Current ( $T_J = 150$ °C)	$I_D$	$T_A = 25$ °C	- 3.1 <sup>a</sup>	A
		$T_A = 70$ °C	- 2.5 <sup>a</sup>	
		$T_A = 25$ °C	- 2.2 <sup>b</sup>	
		$T_A = 70$ °C	- 1.8 <sup>b</sup>	
Pulsed Drain Current	$I_{DM}$	- 15		
Continuous Source-Drain Diode Current	$I_S$	$T_A = 25$ °C	- 0.7 <sup>a</sup>	
		$T_A = 25$ °C	- 0.4 <sup>b</sup>	
Maximum Power Dissipation	$P_D$	$T_A = 25$ °C	0.9 <sup>a</sup>	W
		$T_A = 70$ °C	0.6 <sup>a</sup>	
		$T_A = 25$ °C	0.5 <sup>b</sup>	
		$T_A = 70$ °C	0.3 <sup>b</sup>	
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	- 55 to 150	°C	
Soldering Recommendations (Peak Temperature) <sup>c</sup>		260		

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>a, d</sup>	$R_{thJA}$	105	135	°C/W
Maximum Junction-to-Ambient <sup>b, e</sup>		200	260	

#### Notes:

- Surface mounted on 1" x 1" FR4 board with full copper,  $t = 5$  s.
- Surface mounted on 1" x 1" FR4 board with minimum copper,  $t = 5$  s.
- Refer to IPC/JEDEC (J-STD-020), no manual or hand soldering.
- Maximum under steady state conditions is 185 °C/W.
- Maximum under steady state conditions is 330 °C/W.

SPECIFICATIONS ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$	- 8			V
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = -250\text{ }\mu\text{A}$		- 4		mV/ $^\circ\text{C}$
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			2.1		
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$	- 0.35		- 0.7	V
Gate-Source Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 5\text{ V}$			$\pm 1.5$	$\mu\text{A}$
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -8\text{ V}, V_{GS} = 0\text{ V}$			- 1	
		$V_{DS} = -8\text{ V}, V_{GS} = 0\text{ V}, T_J = 55\text{ }^\circ\text{C}$			- 10	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{DS} \leq -4\text{ V}, V_{GS} = -4.5\text{ V}$	- 5			A
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = -4.5\text{ V}, I_D = -1.5\text{ A}$		0.056	0.068	$\Omega$
		$V_{GS} = -2.5\text{ V}, I_D = -1.5\text{ A}$		0.070	0.088	
		$V_{GS} = -1.5\text{ V}, I_D = -0.5\text{ A}$		0.115	0.155	
		$V_{GS} = -1.2\text{ V}, I_D = -0.3\text{ A}$		0.190	0.290	
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = -4\text{ V}, I_D = -1.5\text{ A}$		8		S
<b>Dynamic<sup>b</sup></b>						
Total Gate Charge	$Q_g$	$V_{DS} = -4\text{ V}, V_{GS} = -4.5\text{ V}, I_D = -1.5\text{ A}$		6.7	10	nC
Gate-Source Charge	$Q_{gs}$			0.7		
Gate-Drain Charge	$Q_{gd}$			1.8		
Gate Resistance	$R_g$	$f = 1\text{ MHz}$		10		$\Omega$
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -4\text{ V}, R_L = 2.7\text{ }\Omega$ $I_D = -1.5\text{ A}, V_{GEN} = -4.5\text{ V}, R_g = 1\text{ }\Omega$		13	25	ns
Rise Time	$t_r$			13	25	
Turn-Off Delay Time	$t_{d(off)}$			25	50	
Fall Time	$t_f$			17	35	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Source-Drain Diode Current	$I_S$	$T_C = 25\text{ }^\circ\text{C}$			- 0.7	A
Pulse Diode Forward Current	$I_{SM}$				- 15	
Body Diode Voltage	$V_{SD}$	$I_S = -1.5\text{ A}, V_{GS} = 0\text{ V}$		- 0.8	- 1.2	V
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F = -1.5\text{ A},$ $di/dt = 100\text{ A}/\mu\text{s}, T_J = 25\text{ }^\circ\text{C}$		35	70	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$			15	30	nC
Reverse Recovery Fall Time	$t_a$			15		ns
Reverse Recovery Rise Time	$t_b$			20		

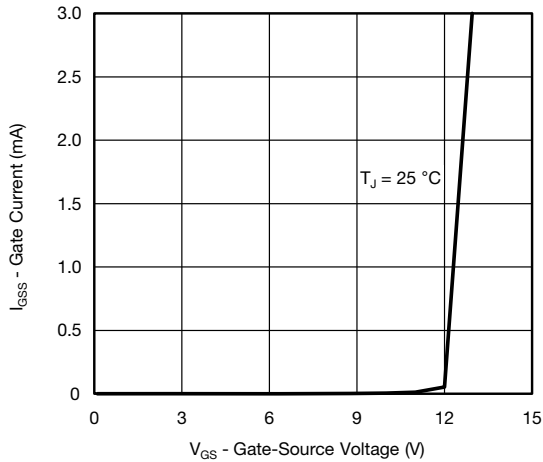
Notes:

- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$   
b. Guaranteed by design, not subject to production testing.

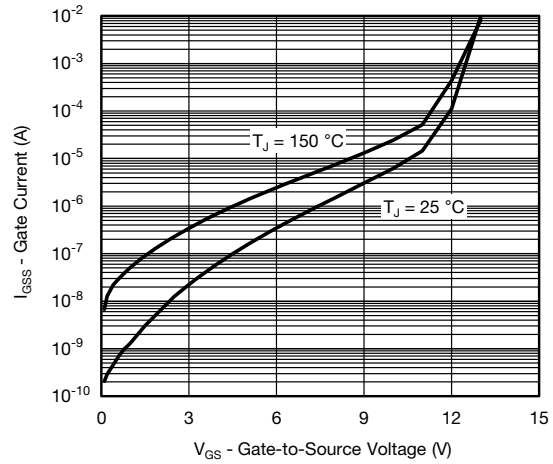
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



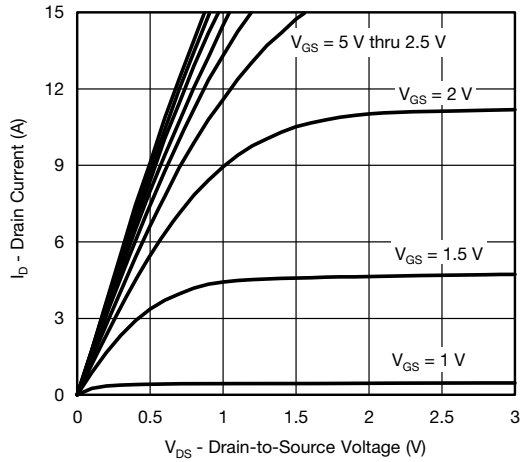
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



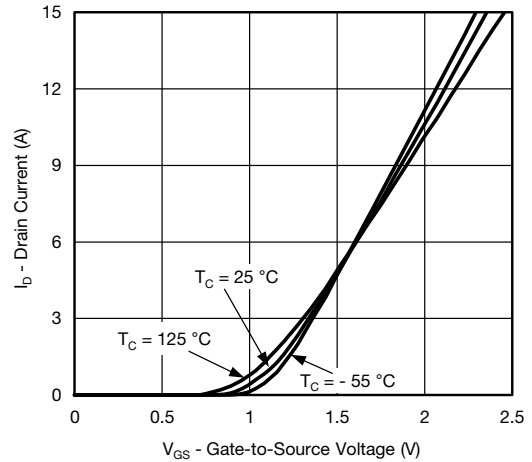
**Gate Current vs. Gate-Source Voltage**



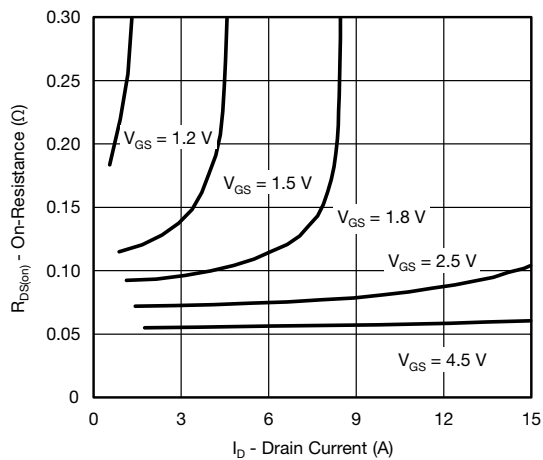
**Gate Current vs. Gate-Source Voltage**



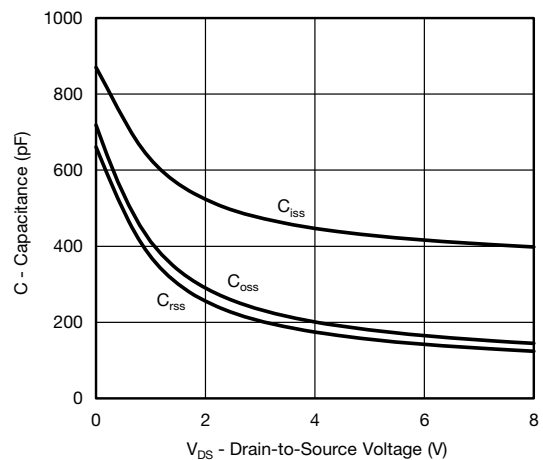
**Output Characteristics**



**Transfer Characteristics**

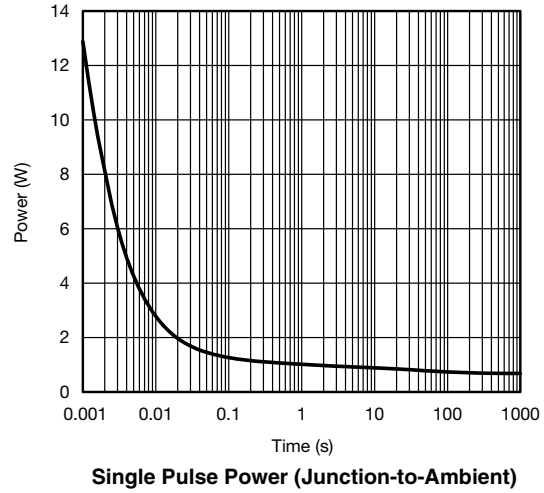
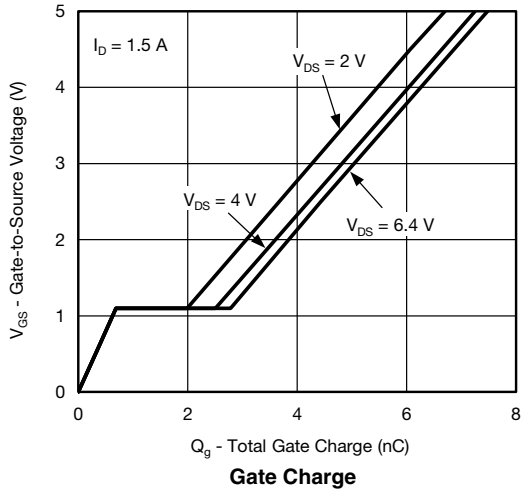


**On-Resistance vs. Drain Current**

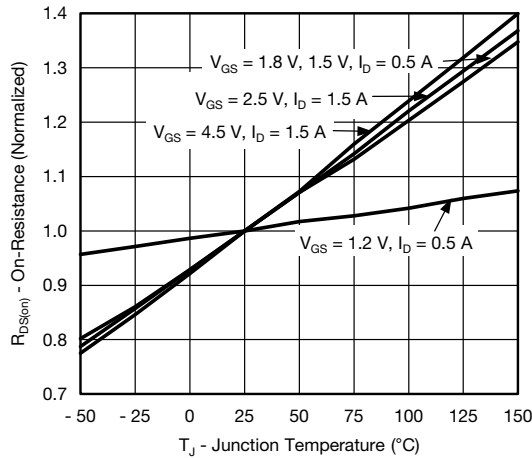


**Capacitance**

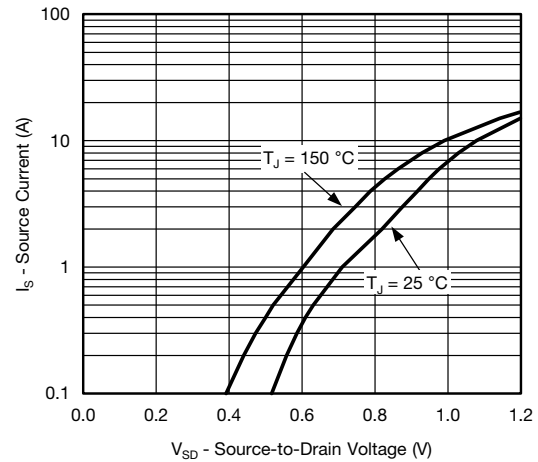
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



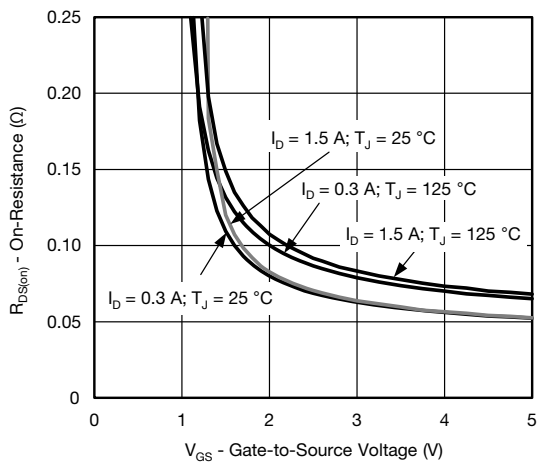
**Single Pulse Power (Junction-to-Ambient)**



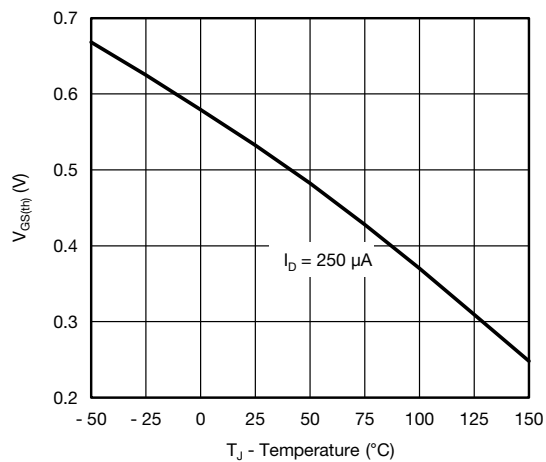
**On-Resistance vs. Junction Temperature**



**Source-Drain Diode Forward Voltage**



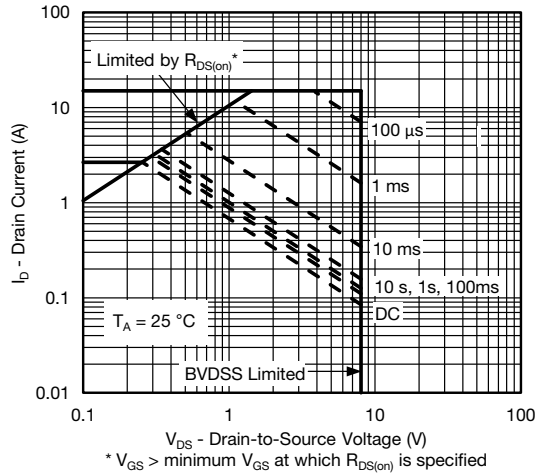
**On-Resistance vs. Gate-to-Source Voltage**



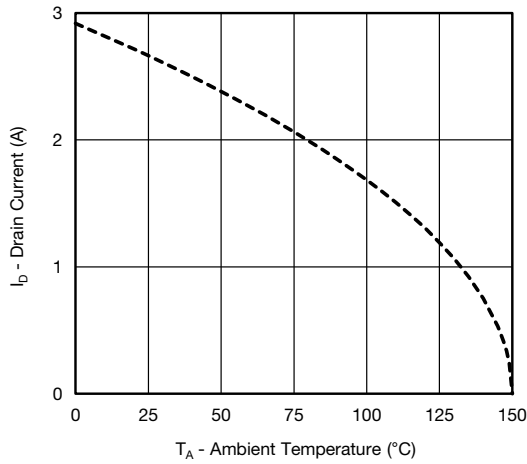
**Threshold Voltage**



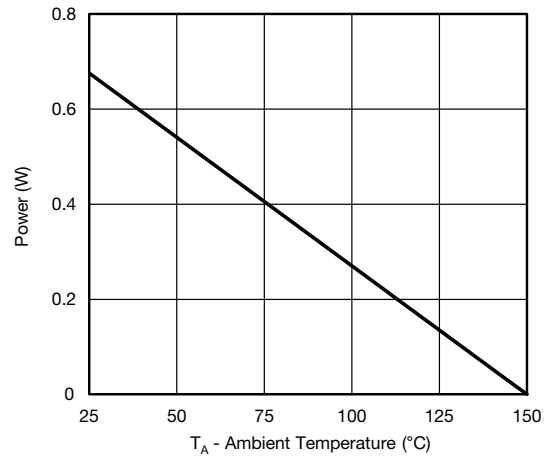
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



**Safe Operating Area, Junction-to-Ambient**



**Current Derating\***

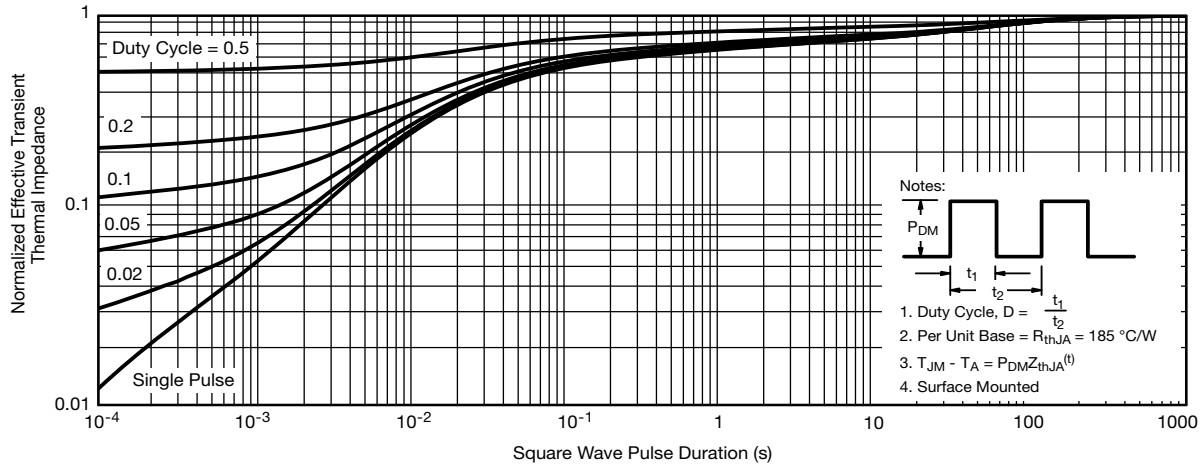


**Power Derating**

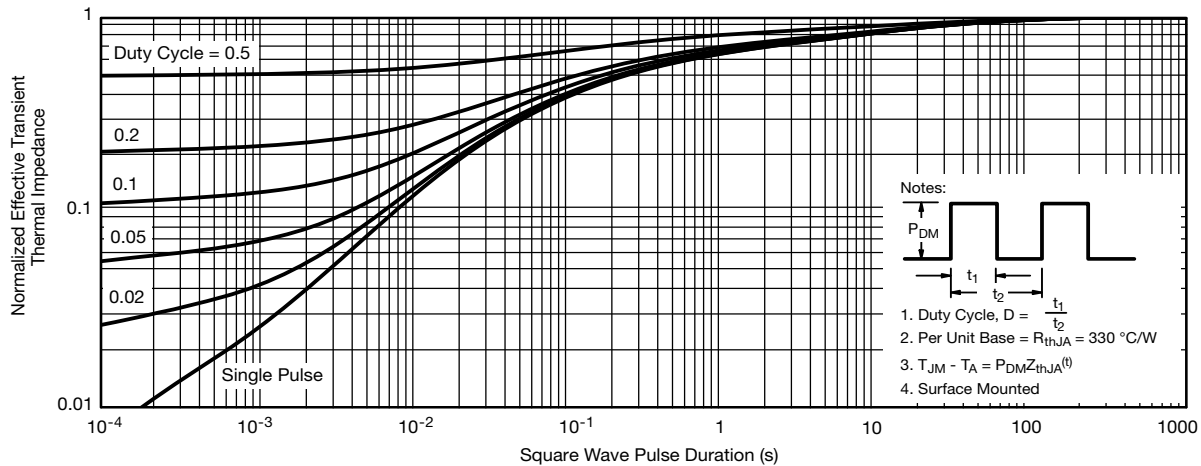
Note:  
When mounted on 1" x 1" FR4 with full copper.

\* The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-ambient thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



**Normalized Thermal Transient Impedance, Junction-to-Ambient (on 1" x 1" FR4 board with maximum copper)**

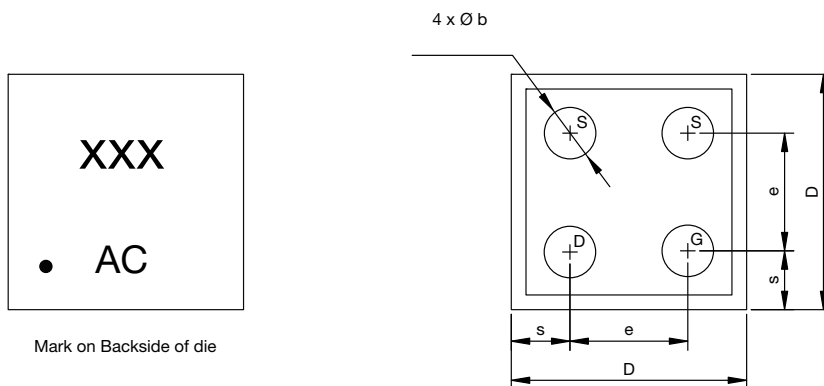


**Normalized Thermal Transient Impedance, Junction-to-Ambient (on 1" x 1" FR4 board with minimum copper)**



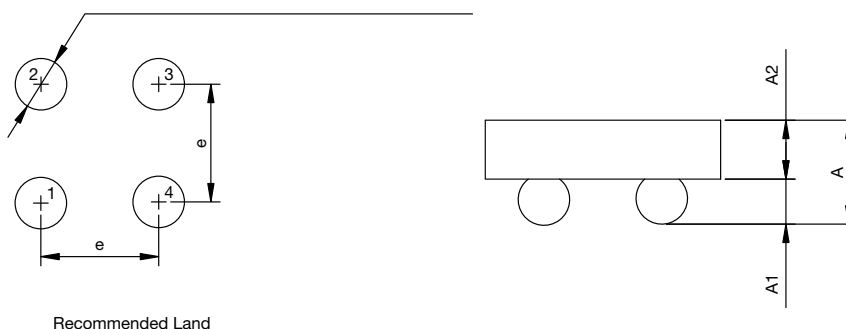
**PACKAGE OUTLINE**

**MICRO FOOT 0.8 mm x 0.8 mm: 4-BUMP (2 x 2, 0.4 mm PITCH)**



Mark on Backside of die

4 x Ø 0.205 to 0.225 Note 4  
Solder Mask ~ Ø 0.215



Recommended Land

Notes (unless otherwise specified):

1. All dimensions are in millimeters.
2. Four (4) solder bumps are lead (Pb)-free 95.5Sn/3.5Ag/0.7Cu with diameter Ø 0.165 mm to Ø 0.185 mm.
3. Backside surface is coated with a Ti/Ni/Ag layer.
4. Non-solder mask defined copper landing pad.
5. • is location of pin 1.

Dim.	Millimeters <sup>a</sup>			Inches		
	Min.	Nom.	Max.	Min.	Nom.	Max.
<b>A</b>	0.314	0.357	0.400	0.0124	0.0141	0.0157
<b>A<sub>1</sub></b>	0.127	0.157	0.187	0.0050	0.0062	0.0074
<b>A<sub>2</sub></b>	0.187	0.200	0.213	0.0074	0.0079	0.0084
<b>b</b>	0.165	0.175	0.185	0.0064	0.0068	0.0072
<b>e</b>		0.400			0.0157	
<b>s</b>	0.180	0.200	0.220	0.0070	0.0078	0.0086
<b>D</b>	0.760	0.800	0.840	0.0299	0.0314	0.0330

Notes:

- a. Use millimeters as the primary measurement.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see [www.vishay.com/ppg?67935](http://www.vishay.com/ppg?67935).



## Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk and agree to fully indemnify and hold Vishay and its distributors harmless from and against any and all claims, liabilities, expenses and damages arising or resulting in connection with such use or sale, including attorneys fees, even if such claim alleges that Vishay or its distributor was negligent regarding the design or manufacture of the part. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

## Material Category Policy

**Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.**

**Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.**